

LEOCO CORPORATION	PRODUCTION SPECIFICATION	No.	S-13-0503	REV	2
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\* 0503(SIDE ENTRY SMT TYPE)SERIES CONNECTER SYSTEM \*

This specification contains the testing methods, the general performance and requirement for interconnection system connector which applied to 0.50mm (.020")ZIF/FPC series connector.

1. Constructions and dimensions shall be in accordance with the drawings attached.

产品结构 and 尺寸依据所提的产品图面

2. Characteristics 特性:

Current rating 额定电流: 0.5A AC/DC

Voltage rating 额定电压: 50V AC/DC

Temperature rating 额定温度: -25°C to +85°C.

3. Electrical performance 电气特性:

Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 要求
3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method EIA-364-23A	40 mΩ max.
3-2	Insulation Resistance 绝缘电阻	It should be tested in accordance with method EIA-364-21B	500MΩ min.
3-3	Dielectric Withstanding Voltage 耐电压	Unmated connector shall be tested in accordance with methoEIA-364-20A.When the DC 200V rms for one minute applied between adjacent contacts.	No evidence of break down and flash over.

4. Mechanical Performance 机械特性:

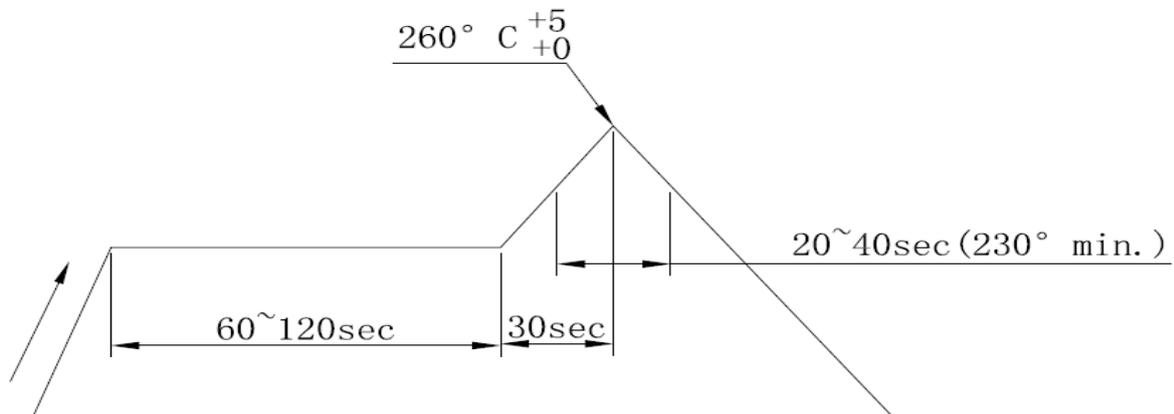
Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 要求
4-1	Terminal retention force 端子保持力	Apply axial pull out force at the speed of 25mm/minute on the assembly in the housing.	0.05Kgf/pin (min)
4.2	FPC/FFC retention force FPC 保持力	Pull out FPC/FFC connector at the speed of 25mm/minute.	n*0.03kgf (min.) n=4~50circuits

5.Environmental Performance 环境特性:

5-1	Humidity 耐湿性	The unmated connector shall be tested in accordance with method EIA-364-31 Temperature : 25°C and 65°C Time of cycle:4 cycles Humidity:90% (rh); Period: 96 hours	No defect. Contact resistance less than twice of initial.
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Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 要求
5-2	Thermal shock 热冲击性	Connector shall be subjected to thermal shock cycling in accordance with EIA-364-32B One cycle consists of: +85°C ± 3°C for 30 min. -25°C ± 2°C for 30 min. Time of cycle: 5 cycles	No defect. Contact resistance less than twice of initial.
5-3	Solder ability 可焊性	Connector termination end shall be checked for solder ability in accordance with method EIA-364-52 Solder temperature: 245 ± 5°C Immersion period: 5 ± 0.5 sec	No damage. Minimum: 90% of immersed area.
5-4	Resistance to Soldering Heat 耐高温焊接	When reflowing Repeat paragraph 6, condition two times. Specimen shall be mounted on PCB. Solder temperature: 260 ± 5°C Immersion period: 5 ± 0.5 sec	No damage and deformation .

6. Infrared Reflow Condition:



TEMPERATURE CONDITION GRAPH

(TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

NOTE: Please check the reflow soldering condition by your own devices beforehand.

Because the condition changes by the soldering devices, P.C.Boards, and so on.

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